

# DATA SHEET

## **74ABT16260**

12-bit to 24-bit multiplexed D-type latch  
(3-State)

Product data

Replaces 74ABT16260/74ABTH16260 dated 1998 Feb 10

2002 Apr 03

## 12-bit to 24-bit multiplexed D-type latch (3-State)

## 74ABT16260

## FEATURES

- ESD protection exceeds 2000 V per Mil-Std-883C, Method 3015; exceeds 200 V using machine model (C = 200 pF, R = 0).
- Latch-up performance exceeds 500 mA per JEDEC Standard JESD-17.
- Distributed  $V_{CC}$  and GND pin configuration minimizes high-speed switching noise.
- Flow-through architecture optimizes PCB layout.
- High-drive outputs ( $-32$  mA  $I_{OH}$ , 64 mA  $I_{OL}$ ).
- Package options:
  - 56-pin plastic Shrink Small-Outline Package (SSOP)
  - 56-pin plastic Thin Shrink Small-Outline Package (TSSOP)

## DESCRIPTION

The 74ABT16260 is a 12-bit to 24-bit multiplexed D-type latch used in applications where two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. This device is also useful in memory-interleaving applications.

Three 12-bit I/O ports (A1–A12, 1B1–1B12, and 2B1–2B12) are available for address and/or data transfer. The output enable ( $\overline{OE1B}$ ,  $\overline{OE2B}$ , and  $\overline{OE A}$ ) inputs control the bus transceiver functions. The  $\overline{OE1B}$  and  $\overline{OE2B}$  control signals also allow bank control in the A-to-B direction.

Address and/or data information can be stored using the internal storage latches. The latch enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch enable input is HIGH, the latch is transparent. When the latch enable input goes LOW, the data present at the inputs is latched and remains latched until the latch enable input is returned HIGH.

To ensure the high-impedance state during power-up or power-down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pull-up resistor; the minimum value of the resistor is determined by the current sinking capability of the driver.

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}\text{C}; \text{GND} = 0\text{V}$	TYPICAL	UNIT
$t_{PLH}$ $t_{PHL}$	Propagation delay nAx to nBx    nBx to nAx	$C_L = 50$ pF	2.8 2.5	ns
$C_{IN}$	Input capacitance	$V_I = 0$ V or $V_{CC}$	4	pF
$C_{OUT}$	Output capacitance	$V_{IO} = 0$ V or 5.0 V	6	pF
$I_{CCZ}$	Total supply current	Outputs disabled	100	$\mu\text{A}$

## ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DWG NUMBER
56-Pin Plastic SSOP Type III	$-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$	74ABT16260DL	SOT371-1
56-Pin Plastic TSSOP Type II	$-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$	74ABT16260DGG	SOT364-1

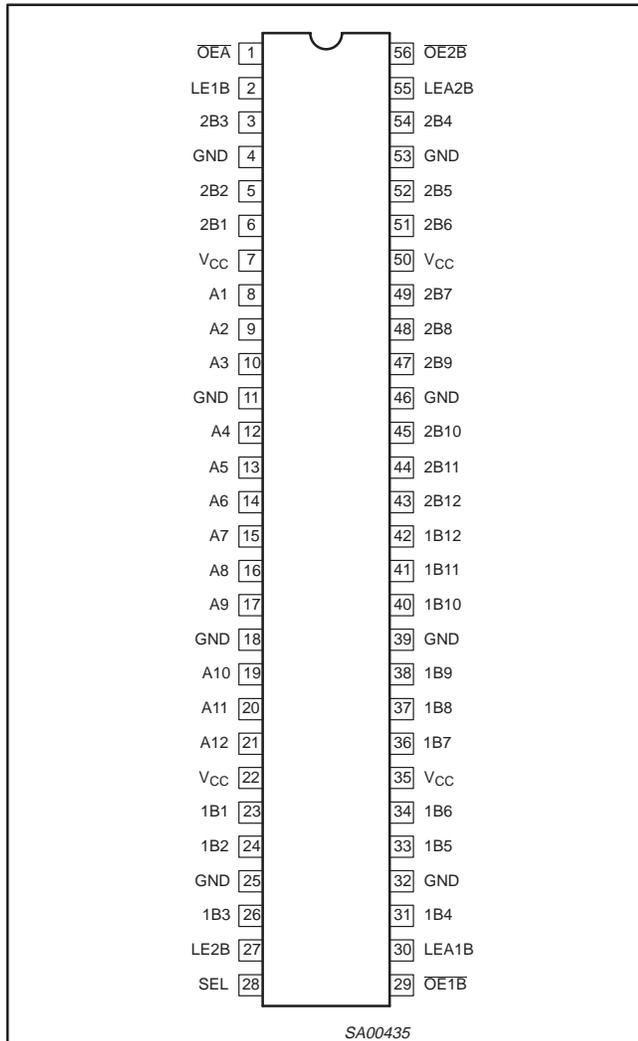
## PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21	A <sub>n</sub>	Data inputs/outputs (A)
23, 24, 26, 31, 33, 34, 36, 37, 38, 40, 41, 42	1B <sub>n</sub>	Data inputs/outputs (B1)
6, 5, 3, 54, 52, 51, 49, 48, 47, 45, 44, 43	2B <sub>n</sub>	Data inputs/outputs (B2)
1, 29, 56	$\overline{OE A}$ , $\overline{OE1B}$ , $\overline{OE2B}$	Output enable input (Active-LOW)
2, 27, 30, 55	LE1B, LE2B, LEA1B, LEA2B	Latch enable inputs

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## PIN CONFIGURATION



## FUNCTION TABLES

### B to A ( $\overline{OE1B} = H$ )

INPUTS						OUTPUT
1B	2B	SEL	LE1B	LE2B	$\overline{OE1B}$	A
H	X	H	H	X	L	H
L	X	H	H	X	L	L
X	X	H	L	X	L	A0
X	H	L	X	H	L	H
X	L	L	X	H	L	L
X	X	L	X	L	L	A0
X	X	X	X	X	H	Z

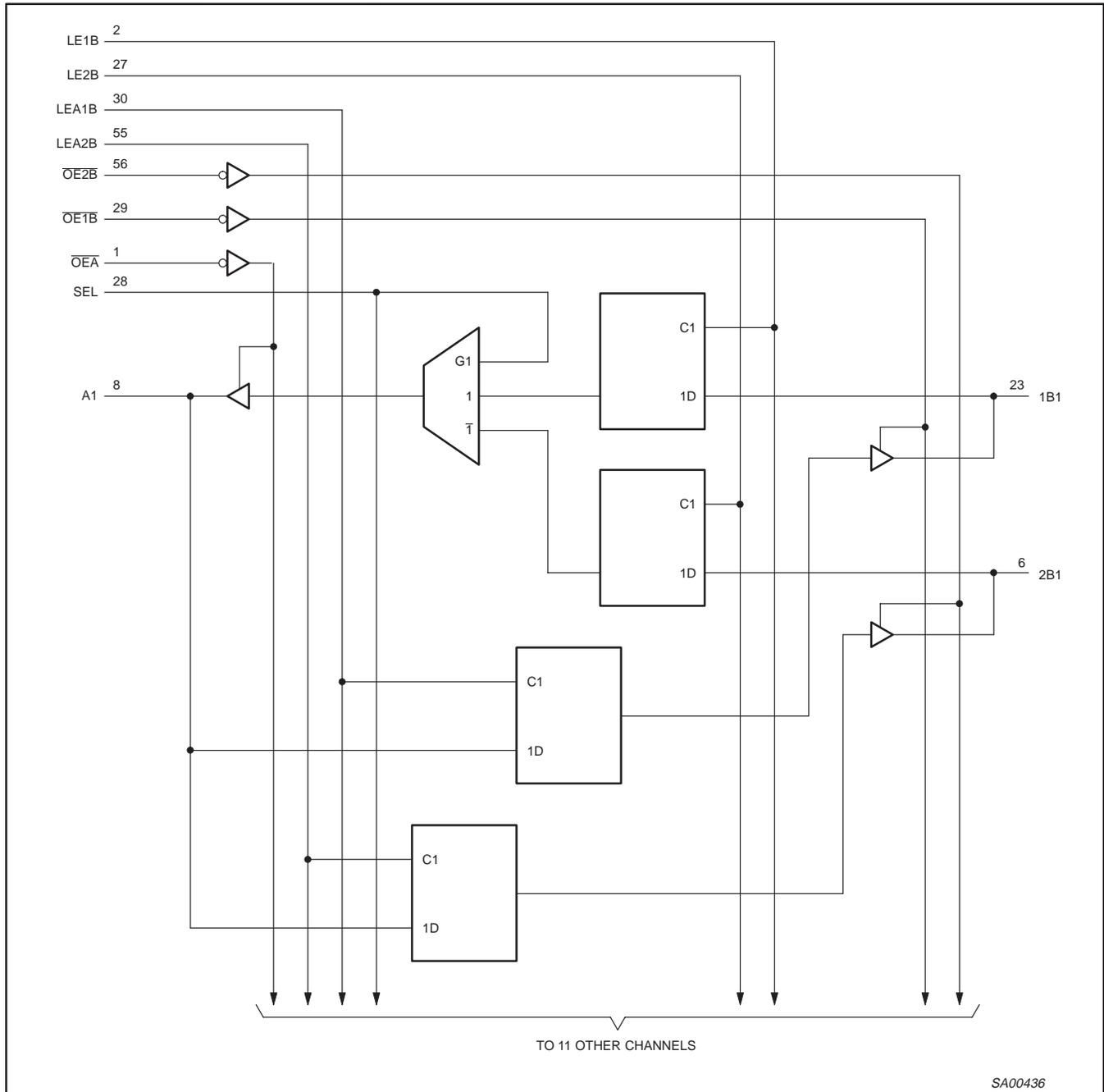
### A to B ( $\overline{OE2B} = H$ )

INPUTS					OUTPUT	
A	LEA1B	LEA2B	$\overline{OE1B}$	$\overline{OE2B}$	1B	2B
H	H	H	L	L	H	H
L	H	H	L	L	L	L
H	H	L	L	L	H	2B0
L	H	L	L	L	L	2B0
H	L	H	L	L	1B0	H
L	L	H	L	L	1B0	L
X	L	L	L	L	1B0	2B0
X	X	X	H	H	Z	Z
X	X	X	L	H	Active	Z
X	X	X	H	L	Z	Active
X	X	X	L	L	Active	Active

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## LOGIC DIAGRAM (POSITIVE LOGIC)



## 12-bit to 24-bit multiplexed D-type latch (3-State)

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**ABSOLUTE MAXIMUM RATINGS**Over operating free-air temperature range (unless otherwise specified)<sup>1</sup>

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V <sub>CC</sub>	Supply voltage range		-0.5	7	V
V <sub>I</sub>	Input voltage range	see Note 2	-0.5	7	V
V <sub>O</sub>	Voltage range applied to any output in the HIGH state or power-off state		-0.5	5.5	V
I <sub>O</sub>	Current into any output in the LOW state		-	128	mA
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-	-18	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-	-50	mA
	Maximum power dissipation at T <sub>amb</sub> = 55 °C (in still air)	see Note 3	-	1.4	W
T <sub>stg</sub>	Storage temperature range		-65	+150	°C

**NOTES:**

- Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils.

**RECOMMENDED OPERATING CONDITIONS<sup>1</sup>**

SYMBOL	PARAMETER		LIMITS		UNIT
			MIN	MAX	
V <sub>CC</sub>	Supply voltage		4.5	5.5	V
V <sub>IH</sub>	HIGH-level input voltage		2	-	V
V <sub>IL</sub>	LOW-level input voltage		-	0.8	V
V <sub>I</sub>	Input voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	HIGH-level output current		-	-32	mA
I <sub>OL</sub>	LOW-level output current		-	64	mA
ΔtΔ/v	Input transition rise or fall rate	Outputs enabled	-	10	ns/V
ΔtΔ/V <sub>CC</sub>	Power-up ramp rate		200	-	μs/V
T <sub>amb</sub>	Operating free-air temperature		-40	+85	°C

**NOTE:**

- Unused or floating inputs must be held HIGH or LOW.

## 12-bit to 24-bit multiplexed D-type latch (3-State)

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## DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T <sub>amb</sub> = +25 °C			T <sub>amb</sub> = -40 °C to +85 °C		
			Min	Typ	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5 V; I <sub>IK</sub> = -18 mA	-	-0.8	-1.2	-	-1.2	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>CC</sub> = 4.5 V; I <sub>OH</sub> = -3 mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.5	2.9	-	2.5	-	V
		V <sub>CC</sub> = 5.0 V; I <sub>OH</sub> = -3 mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	3.0	3.4	-	3.0	-	V
		V <sub>CC</sub> = 4.5 V; I <sub>OH</sub> = -32 mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.0	2.4	-	2.0	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>CC</sub> = 4.5 V; I <sub>OL</sub> = 64 mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	-	0.42	0.55	-	0.55	V
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = V <sub>CC</sub> or GND	-	±0.01	±1	-	±1	μA
		V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = V <sub>CC</sub> or GND	-		±3	-	±5	μA
I <sub>OFF</sub>	Power-off leakage current	V <sub>CC</sub> = 0.0 V; V <sub>O</sub> or V <sub>I</sub> ≤ 4.5 V	-	±5.0	±100	-	±100	μA
I <sub>PU</sub> /I <sub>PD</sub>	Power-up/down 3-State output current	V <sub>CC</sub> = 2.0 V; V <sub>O</sub> = 0.5 V; V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>OE</sub> = V <sub>CC</sub>	-	±60	±200	-	±200	μA
I <sub>OZH</sub>	3-State output HIGH current	V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = 2.7 V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	-	1.0	10	-	10	μA
I <sub>OZL</sub>	3-State output LOW current	V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = 0.5 V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	-	-1.0	-10	-	-10	μA
I <sub>CEX</sub>	Output HIGH leakage current	V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = 5.5 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-		50	-	50	μA
I <sub>O</sub>	Output current <sup>1</sup>	V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = 2.5 V	-50	-100	-225	-50	-225	mA
I <sub>CC</sub>	Quiescent supply current	V <sub>CC</sub> = 5.5 V; Outputs HIGH, V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.2	1.5	-	1.5	mA
		V <sub>CC</sub> = 5.5 V; Outputs LOW, V <sub>I</sub> = GND or V <sub>CC</sub>	-	8	19	-	19	mA
		V <sub>CC</sub> = 5.5 V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.1	1.0	-	1.0	mA
ΔI <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>	Outputs enabled, one input at 3.4 V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	0.1	1.5	-	1.5	mA

## NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

## 12-bit to 24-bit multiplexed D-type latch (3-State)

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**AC ELECTRICAL CHARACTERISTICS**

Over recommended operating free-air temperature range (unless otherwise noted).

SYMBOL	PARAMETER		$V_{CC} = 5\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$		UNIT
	FROM (INPUT)	TO (OUTPUT)	MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A or B	B or A	1	2.8	4.8	1	5.6	ns
$t_{PHL}$			1	2.5	5	1	5.9	ns
$t_{PLH}$	$\overline{LE}$	A or B	1.1	3.2	4.9	1.1	5.8	ns
$t_{PHL}$			1.1	3.2	4.9	1.1	5.3	ns
$t_{PLH}$	SEL (B1)	A	1.3	3.2	4.6	1.3	5.3	ns
	SEL (B2)	A	1.1	2.8	4.9	1.1	6	ns
$t_{PHL}$	SEL (B1)	A	1.5	3.0	4.4	1.5	4.4	ns
	SEL (B2)	A	1.6	2.6	5.1	1.6	5.9	ns
$t_{PZH}$	$\overline{OE}$	A or B	1	2.9	4.7	1	5.7	ns
$t_{PZL}$			1.6	2.2	5.1	1.6	5.8	ns
$t_{PHZ}$	$\overline{OE}$	A or B	2.2	4.1	5.4	2.2	6.4	ns
$t_{PLZ}$			1.3	3.2	4.4	1.3	4.8	ns

**AC SETUP CHARACTERISTICS**

Over recommended operating free-air temperature range (unless otherwise noted).

SYMBOL	PARAMETER	$V_{CC} = 5\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$		$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$		UNIT
		MIN	MAX	MIN	MAX	
$t_w$	Pulse duration, LE1B, LE2B, LEA1B, or LEA2B HIGH	3.3	–	3.3	–	ns
$t_{su}$	Set-up time, data before LE1B, LE2B, LEA1B, or LEA2B↓	1.5	–	1.5	–	ns
$t_h$	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B↓	1	–	1	–	ns

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## AC WAVEFORMS

$V_M = 1.5\text{ V}$  for all waveforms

The outputs are measured one at a time with one transition per measurement.

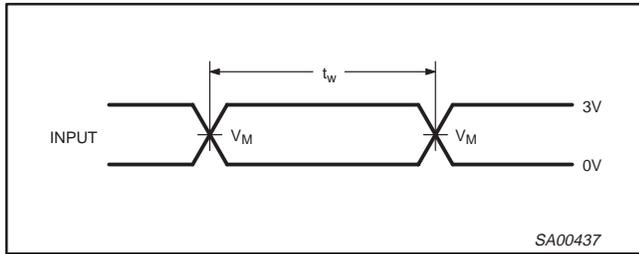


Figure 1. Pulse duration

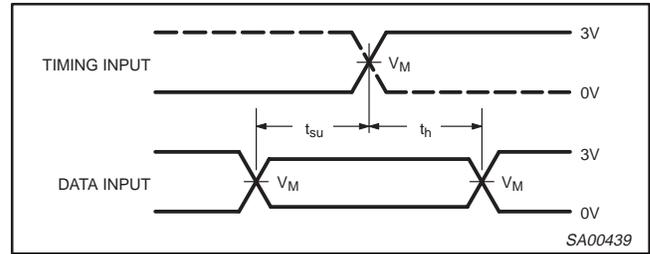


Figure 3. Set-up and hold times

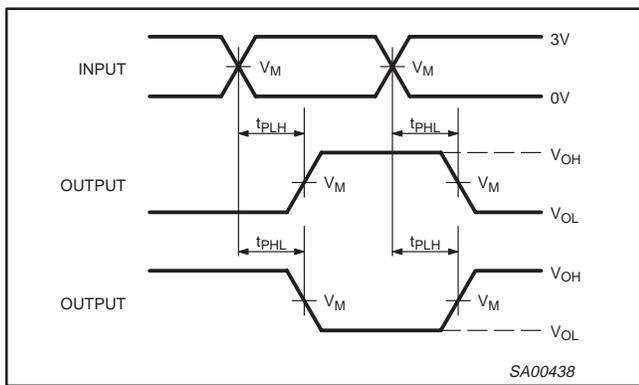


Figure 2. Propagation delay times; inverting and non-inverting outputs

All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2.5\text{ ns}$ ,  $t_f \leq 2.5\text{ ns}$ .

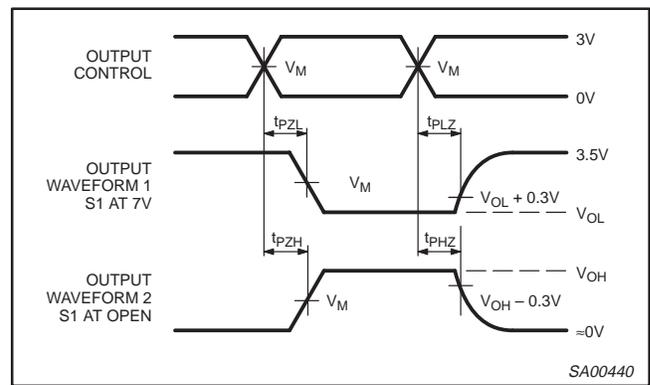


Figure 4. Enable and disable times; LOW- and HIGH-level enabling

Waveform 1 is for an output with internal conditions such that the output is LOW except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is HIGH except when disabled by the output control.

## TEST LOAD CIRCUIT

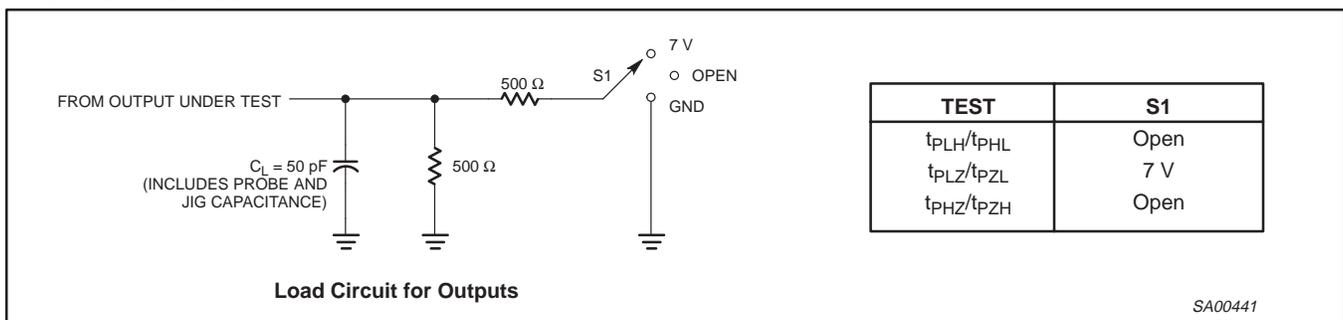


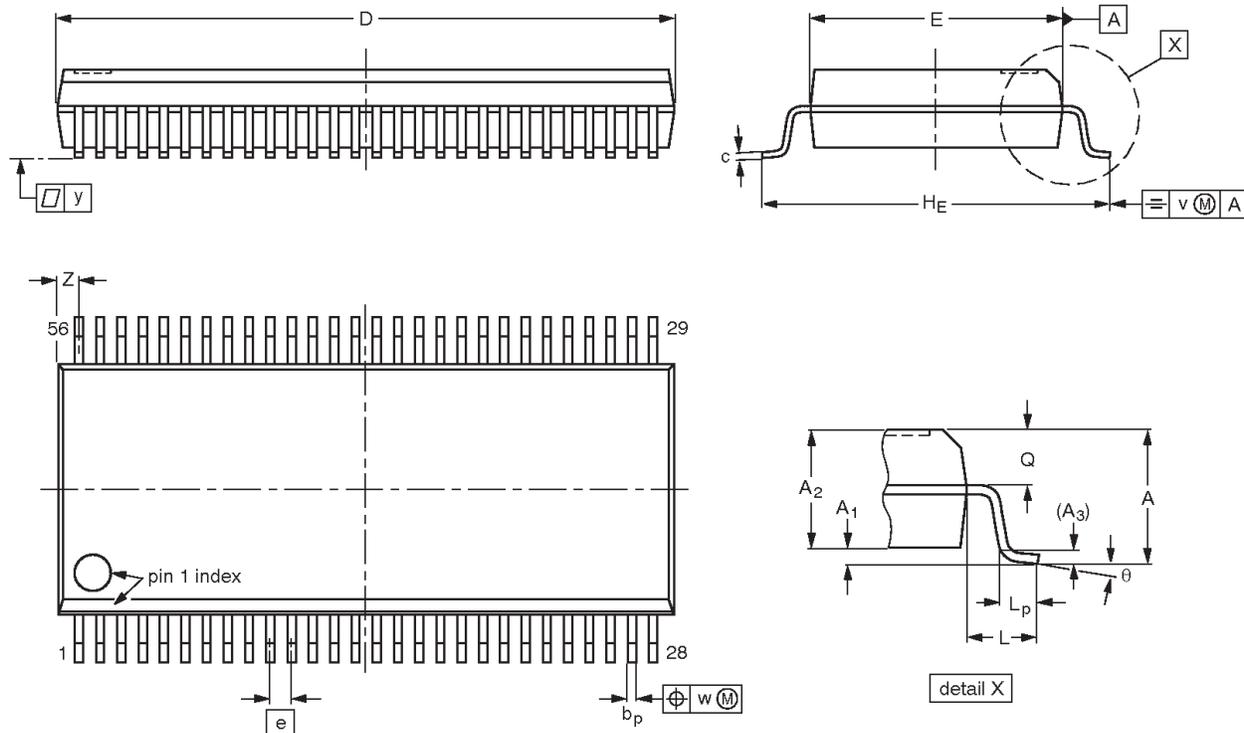
Figure 5. Test load circuit

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**SSOP56:** plastic shrink small outline package; 56 leads; body width 7.5 mm

**SOT371-1**



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

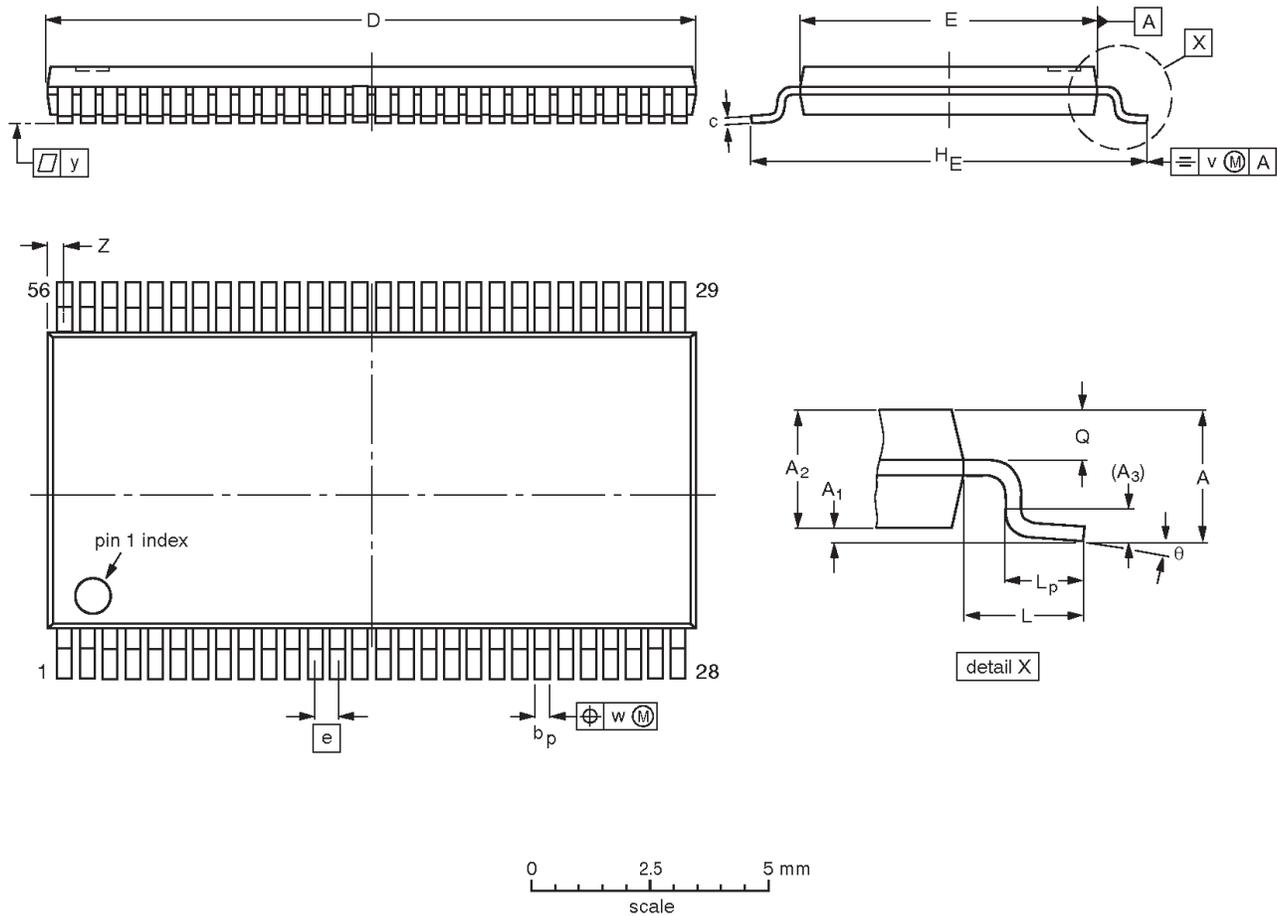
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT371-1		MO-118				95-02-04 99-12-27

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TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm

SOT364-1



**DIMENSIONS (mm are the original dimensions).**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT364-1		MO-153				-95-02-10 99-12-27

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**NOTES**

## 12-bit to 24-bit multiplexed D-type latch (3-State)

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## Data sheet status

Data sheet status <sup>[1]</sup>	Product status <sup>[2]</sup>	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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